

WHAT IS CLAIMED IS:

1. A heat dissipating structure of a printed circuit board on which a circuit pattern is provided so that a heat generating part can be
5 mounted, and which has a through hole formed at a site where the heat generating part is mounted from a surface on which the heat generating part is mounted to the opposite surface, wherein a heat dissipating member made of a material with a thermal conductivity higher than a board of the printed circuit board, and having a shape worked so that
10 the heat dissipating member can be inserted into the through hole is mounted in the through hole with an adhesive interposed therebetween.

2. The heat dissipating structure of the printed circuit board of Claim 1, wherein a heat transfer plate made of a material with a
15 thermal conductivity higher than the printed circuit board is adhered on the heat dissipating member of the printed circuit board and heat generated by a heat generating part mounted on the heat transfer plate is dissipated to the heat dissipating member by way of the heat transfer plate.

20

3. A method of fabricating a heat dissipating structure of a printed circuit board on which a circuit pattern is provided so that a heat generating part can be mounted, and which has a through hole formed at a site where the heat generating part is mounted from a surface on
25 which the heat generating part is mounted to the opposite surface, a heat dissipating member being mounted in the through hole, comprising the steps of: blocking one opening of the through hole formed in the

printed circuit board with a heat resistant tape; inserting the heat dissipating member, made of a material with a thermal conductivity higher than a board of the printed circuit board, and having a shape worked so that the heat dissipating member can be inserted into the
5 through hole, into the through hole from the other opening of the through hole; fixing the heat dissipating member by putting an adhesive into a clearance between the through hole and the heat dissipating member to cure the adhesive; and removing the heat resistant tape from the printed circuit board.

10

4. A method of fabricating a heat dissipating structure of a printed circuit board on which a circuit pattern is provided so that a heat generating part can be mounted, and which has a through hole formed at a site where the heat generating part is mounted from a surface on
15 which the heat generating part is mounted to the opposite surface, a heat dissipating member being mounted in the through hole, comprising the steps of: working shapes of the through hole and the heat dissipating member so that the heat dissipating member made of a material with a thermal conductivity higher than a board of the printed circuit board is
20 supported in the through hole to insert the heat dissipating member into the through hole for provisional fixation; and fixing the heat dissipating member by putting an adhesive into a clearance between the through hole and the heat dissipating member to cure the adhesive.

25

5. The method of any one of Claims 3 to 4, wherein the step of putting the adhesive into a clearance between the through hole and the heat dissipating member to cure the adhesive and to fix the heat

dissipating member is performed in a procedure in which the adhesive is not only put into a clearance between the through hole and the heat dissipating member, but also attached onto the heat dissipating member, a heat generating part is mounted onto the heat dissipating member, and thereafter the adhesive is cured, whereby the through hole and the heat dissipating member, and the heat dissipating member and the heat generating part are collectively fixed simultaneously.